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B1 41. (Amended) The method of claim ¹40 wherein the pre-selected pulse shape is a pre-selected pulse width.

⁶ 45. (Amended) The method of claim ¹40 wherein the target material is a thick-film electrical element.

⁷ 46. (Amended) The method of claim ¹40 wherein the target material is a thin-film electrical element.

⁸ 47. (Amended) The method of claim ¹40 wherein the target material is a resistor.

⁹ 48. (Amended) The method of claim ¹40 wherein the target material is a capacitor.

¹⁰ 49. (Amended) The method of claim ¹40 wherein the target material is a conductive link.

¹³ 52. (Amended) The method of claim ¹40 wherein the laser source comprises a laser pump and a laser rod, and the pulsed laser system comprises a switch that, when closed in an on state, causes energy from the laser pump to be stored in the laser and that, when opened in an off state, allows energy to be emitted from the laser rod during an emission period.

¹⁶ 55. (Amended) A method of operating a pulsed laser system comprising:
providing a pulsed laser system comprising a laser source;
presetting a pre-selected repetition rate at which the pulsed laser system is to be operated, based on known properties of a target material to be processed on a workpiece;
selecting a pulse shape independently of the pre-selected repetition rate; and
pulsing the pulsed laser system with the pulse shape selected independently of the pre-selected repetition rate, to cause the laser source to process the target material on the workpiece, while the pre-selected repetition rate remains as preset regardless of the pulse shape, without selection of the pulse shape affecting the repetition rate.

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56. (Amended) The method of claim 55 wherein the pre-selected pulse shape is a pre-selected pulse width.

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26 21 60. (Amended) The method of claim 55 wherein the target material is a thick-film electrical element.

16 21
27 22 61. (Amended) The method of claim 55 wherein the target material is a thin-film electrical element.

B5 28 23 62. (Amended) The method of claim 55 wherein the target material is a resistor.

29 24 63. (Amended) The method of claim 55 wherein the target material is a capacitor.

30 25 64. (Amended) The method of claim 55 wherein the target material is a conductive link.

B6 33 28 67. (Amended) The method of claim 55 wherein the laser source comprises a laser pump and a laser rod, and the pulsed laser system comprises a switch that, when closed in an on state, causes energy from the laser pump to be stored in the laser and that, when opened in an off state, allows energy to be emitted from the laser rod during an emission period.

Please add new claims 70-75:

36 35 70. The method of claim 40 wherein the target material is a trimmable component and the step of selecting a repetition rate is performed dynamically during trimming of the trimmable component so as to permit the trimmable component to be measured accurately during trimming of the trimmable component.

B7 37 32 36 35 71. The method of claim 70 wherein the step of presetting a pre-selected pulse shape is performed so as to allow the trimmable component to be cut all the way through the trimmable component without undue heating.